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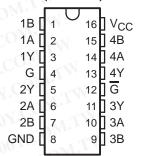
- Designed for TIA/EIA-485, TIA/EIA-422, and ISO 8482 Applications
- Signaling Rate<sup>†</sup> Exceeding 50 Mbps
- Fail-Safe in Bus Short-Circuit, Open-Circuit, and Idle-Bus Conditions
- ESD Protection on Bus Inputs Exceeds 6 kV
- Common-Mode Bus Input Range
   7 V to 12 V
- Propagation Delay Times <16 ns</li>
- Low Standby Power Consumption <20 μA</li>
- Pin-Compatible Upgrade for AM26LS32, DS96F173, LTC488, and SN75173

# description

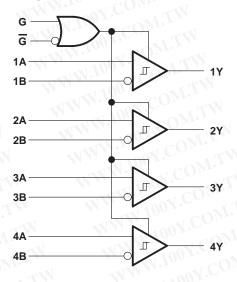
The SN65LBC173A and SN75LBC173A are quadruple differential line receivers with 3-state outputs, designed for TIA/EIA-485 (RS-485), TIA/EIA-422 (RS-422), and ISO 8482 (Euro RS-485) applications.

These devices are optimized for balanced multipoint bus communication at data rates up to and exceeding 50 million bits per second. The transmission media may be twisted-pair cables, printed-circuit board traces, or backplanes. The ultimate rate and distance of data transfer is dependent upon the attenuation characteristics of the media and the noise coupling to the environment.

SN65LBC173A (Marked as 65LBC173A) SN75LBC173A (Marked as 75LBC173A) D or N PACKAGE (TOP VIEW)



# logic diagram



Each receiver operates over a wide range of positive and negative common-mode input voltages, and features ESD protection to 6 kV, making it suitable for high-speed multipoint data transmission applications in harsh environments. These devices are designed using LinBiCMOS™, facilitating low power consumption and robustness.

The G and  $\overline{G}$  inputs provide enable control logic for either positive- or negative-logic enabling all four drivers. When disabled or powered off, the receiver inputs present a high-impedance to the bus for reduced system loading.

The SN75LBC173A is characterized for operation over the temperature range of 0°C to 70°C. The SN65LBC173A is characterized over the temperature range from –40°C to 85°C.





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

LinBiCMOS is a trademark of Texas Instruments.

†The signaling rate of a line is the number of voltage transitions that are made per second expressed in the units bps (bits per second)



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#### **FUNCTION TABLE** (each receiver)

DIFFERENTIAL INPUTS	ENA	BLES	OUTPUT
A – B (V <sub>ID</sub> )	G	G	Y
ACON CONTRACTOR	H 📢	X	N.Co
$V_{ID} \le -0.2 \text{ V}$	X		V.COD
100V V C004V	Н	X	160
$-0.2 \text{ V} < \text{V}_{\text{ID}} < -0.01 \text{ V}$	Х	L	0015
MAN CONTRACT	n H	X	100X.C
-0.01 V ≤ V <sub>ID</sub>	X	L	T H
MON TOWN	L	Н	11.100
MM X 100 X . C .	OPEN	OPEN	01.160x
William and DOM.	TH	X	1.00
Short circuit	X	L	H
Open circuit	M·H	Х	HIV

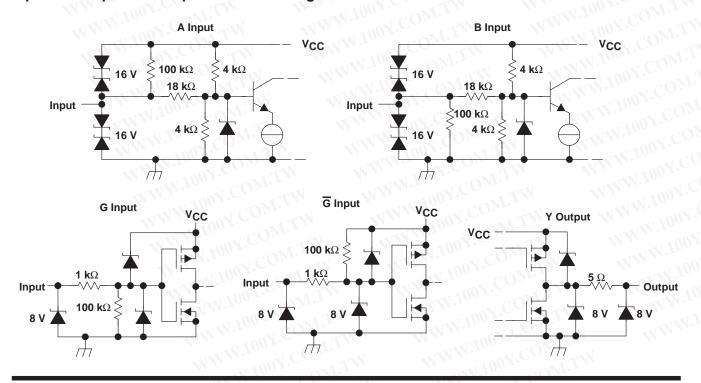
H = high level, L = low level, X = irrelevant, Z = high impedance (off), ? = indeterminate

#### **AVAILABLE OPTIONS**

MM.	PACE	KAGE
T <sub>A</sub> W	PLASTIC SMALL OUTLINE <sup>†</sup> (JEDEC MS-012)	PLASTIC DUAL-IN-LINE (JEDEC MS-001)
0°C to 70°C	SN75LBC173AD	SN75LBC173AN
-40°C to 85°C	SN65LBC173AD	SN65LBC173AN

<sup>†</sup> Add an R suffix for taped and reeled

# equivalent input and output schematic diagrams





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# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub> (see Note 1)		–0.3 V to 6 V
Voltage range at any bus input (DC)		
Voltage range at any bus input (transient p	oulse through 100 $\Omega$ , see Figu	ure 5)
Voltage input range at G and G, V <sub>I</sub>		$-0.5 \text{ V}$ to $V_{CC} + 0.5 \text{ V}$
Receiver output current, IO	1:70 <sub>031</sub> ,	±10 mA
Electrostatic discharge:		
Human body model (see Note 2):	A and B to GND	6 kV
		5 kV
Charged-device model (see Note 3):	All pins	
Continuous power dissipation		See Power Dissipation Rating Table

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential I/O bus voltages, are with respect to GND, and are steady-state (unless otherwise specified).

- 2. Tested in accordance with JEDEC Standard 22, Test Method A114-A.
- 3. Tested in accordance with JEDEC Standard 22, Test Method C101.

#### **DISSIPATION RATING TABLE**

PACKAGE	T <sub>A</sub> ≤ 25°C POWER RATING	DERATING FACTOR‡ ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 70°C POWER RATING	T <sub>A</sub> = 85°C POWER RATING
D	1080 mW	8.7 mW/°C	690 mW	560 mW
N	1150 mW	9.2 mW/°C	736 mW	598 mW

<sup>&</sup>lt;sup>‡</sup> This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

# recommended operating conditions

MAN TO COMP	N NWW. DOY. COME TW WY	MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>	COM.	4.75	5	5.25	V
Voltage at any bus terminal	A, B	-7	100 -	12	٧
High-level input voltage, VIH	The Marianovice Milliam A	2	11007	VCC	VII.
Low-level input voltage, V <sub>IL</sub>	G, G	0	100	0.8	V
Output current	Y Y COM	-8	11.10	8	mA
W 1002.	SN75LBC173A	0	W.10	70	$0_{M}$
Operating free-air temperature, T <sub>A</sub>	SN65LBC173A	-40	11	85	ç



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# electrical characteristics over recommended operating conditions

-11	PARAMETE	R	TEST CO	ONDITIONS	MIN	TYP <sup>†</sup>	MAX	UNIT
V <sub>IT+</sub>	Positive-going differential i	nput voltage threshold		1007	IM	-80	-10	
V <sub>IT</sub> _	Negative-going differential	input voltage threshold	$-7 \text{ V} \leq \text{V}_{CM} \leq 12 \text{ V}$	$(V_{CM} = (V_A + V_B)/2)$	-200	-120		mV
VHYS	Hysteresis voltage (V <sub>IT+</sub> -	- V <sub>IT</sub> -)		MM.Ing COV	1 XX	40		mV
VIK	Input clamp voltage	1007.	I <sub>I</sub> = -18 mA	1001	-1.5	-0.8		V
Vон	High-level output voltage	M. 100X.CO	$V_{ID} = 200 \text{ mV},$ $I_{OH} = -8 \text{ mA}$	MM. 100X.C	2.7	4.8		
VOL	Low-level output voltage	MMM.1007.C	$V_{ID} = -200 \text{ mV},$ $I_{OL} = 8 \text{ mA}$	See Figure 1	OM	0.2	0.4	V
loz	High-impedance-state out	put current	VO = 0 V to VCC	WWW.	CO-1	WT	1	μΑ
700.	. COM:	W. 100 -	Other input at 0 V,	V <sub>I</sub> = 12 V	COD	1.	0.9	
1 100	Line input current		$V_{CC} = 0 \text{ V or 5 V}$	V <sub>I</sub> = -7 V	-0.7	Mil	-4	mA
l <sub>IH</sub>	High-level input current	- 1/1/1/ - = 0	S.CO. TW	11/11/10	N.C.	TILL	100	μΑ
1	Low-level input current	Enable inputs G, G	V.COM.	WWW	-100	O 14	W	μΑ
R <sub>I</sub>	Input resistance	A, B inputs	COM	I.WW.I	12	$COM_{I}$ .		kΩ
VV .	1007. OM.TW	11	V <sub>ID</sub> = 5 V	G at 0 V, G at V <sub>CC</sub>	100 -	COM	20	μΑ
ICC	Supply current		No load	G at V <sub>CC</sub> , G at 0 V	1007	11	16	mA

<sup>†</sup> All typical values are at V<sub>CC</sub> = 5 V and 25°C.

# switching characteristics over recommended operating conditions

WW	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
tr	Output rise time	ALCON TW	MAN	2.	4	ns
tf	Output fall time	V CON	WW	2	(4)	ns
t <sub>PLH</sub>	Propagation delay time, low-to-high level output	$V_{ID} = -3 \text{ V to } 3 \text{ V}, \text{ See Figure } 2$	9	12	16	ns
t <sub>PHL</sub>	Propagation delay time, high-to-low level output	OOY.CO TITY	9	12	16	ns
<sup>t</sup> PZH	Propagation delay time, high-impedance to high-level output	ON COM	WW	27	38	ns
<sup>t</sup> PHZ	Propagation delay time, high-level to high-impedance output	See Figure 3		7 7	16	ns
tpzL	Propagation delay time, high-impedance to low level output	1700x.	44	29	38	ns
<sup>t</sup> PLZ	Propagation delay time, low-level to high-impedance output	See Figure 4		12	16	ns
tsk(p)	Pulse skew (  (tpLH - tpHL)  )	N. T. CO.		0.2	101	ns
tsk(o)	Output skew (see Note 4)	M. Inc. COM.			2	ns
tsk(pp)	Part-to-part skew (see Note 5)	W.100 1. COM: 1.		111	2	ns

<sup>&</sup>lt;sup>†</sup> All typical values are at V<sub>CC</sub> = 5 V and 25°C.

NOTES: 4. Outputs skew (t<sub>Sk(o)</sub>) is the magnitude of the time delay difference between the outputs of a single device with all of the inputs connected together.

5. Part-to-part skew (tsk(pp)) is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same input signals, the same supply voltages, at the same temperature, and have identical packages and test circuits.



# PARAMETER MEASUREMENT INFORMATION

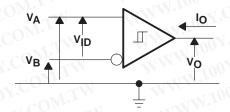


Figure 1. Voltage and Current Definitions

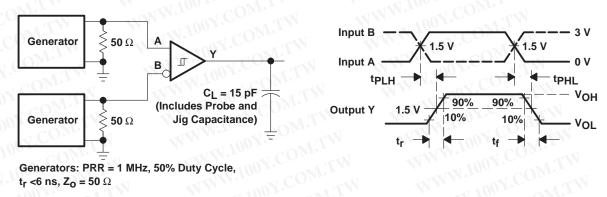


Figure 2. Switching Test Circuit and Waveforms

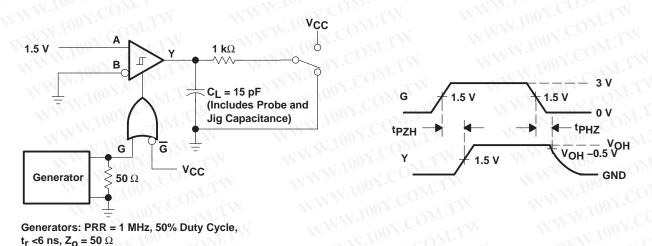
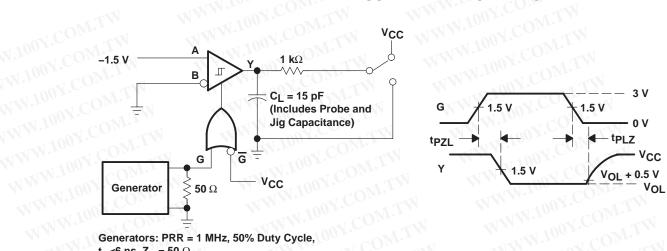


Figure 3. Test Circuit Waveforms, tpzH and tpHZ

# PARAMETER MEASUREMENT INFORMATION



 $t_r$  <6 ns,  $Z_0$  = 50  $\Omega$ 

Figure 4. Test Circuit Waveforms, tpzL and tpLZ

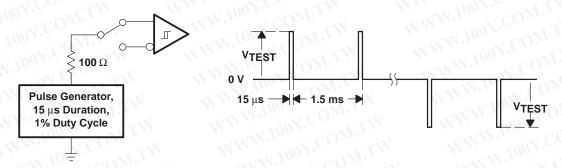
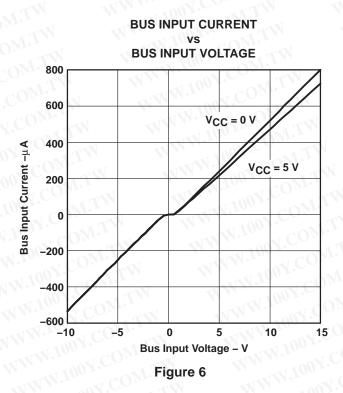
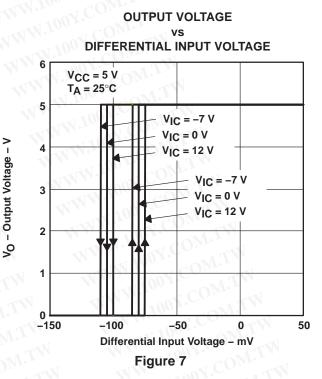


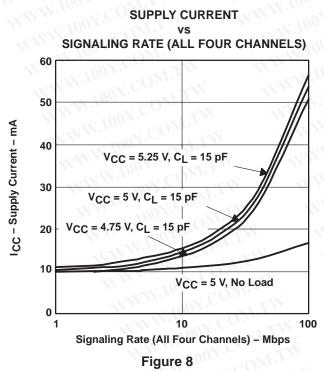
Figure 5. Test Circuit and Waveform, Transient Over-Voltage Test

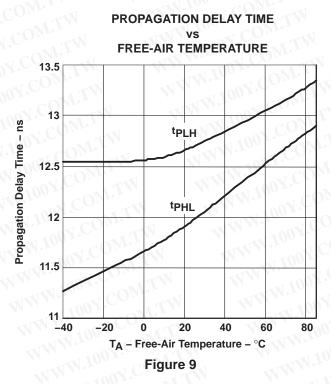
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# TYPICAL CHARACTERISTICS



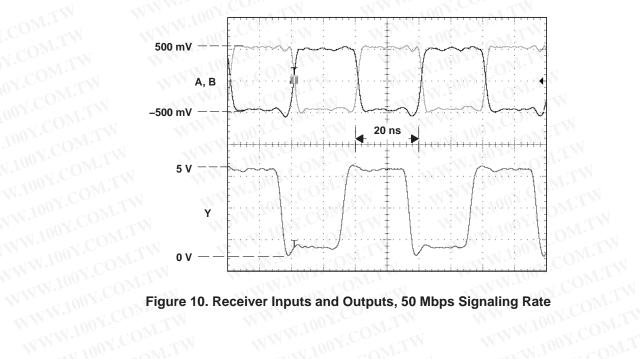






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#### TYPICAL CHARACTERISTICS



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# **APPLICATION INFORMATION**

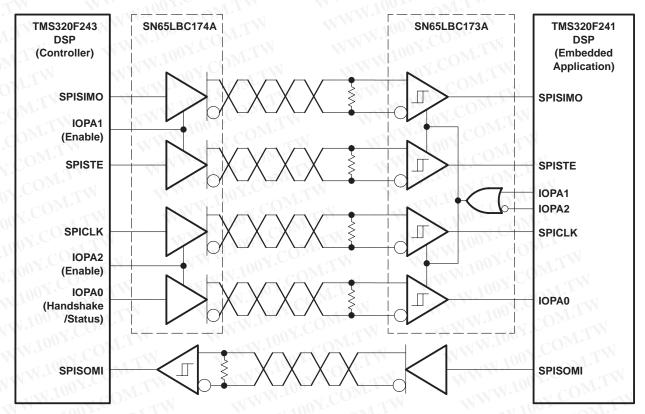


Figure 11. Typical Application Circuit, DSP-to-DSP Link via Serial Peripheral Interface

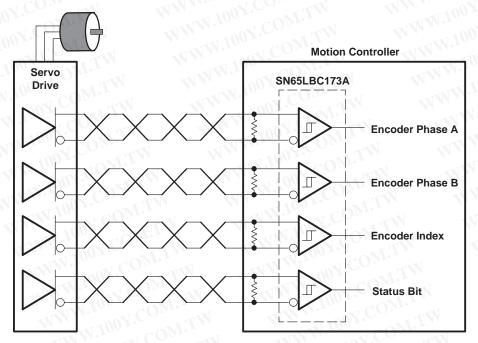


Figure 12. Typical Application Circuit, High-Speed Servomotor Encoder Interface



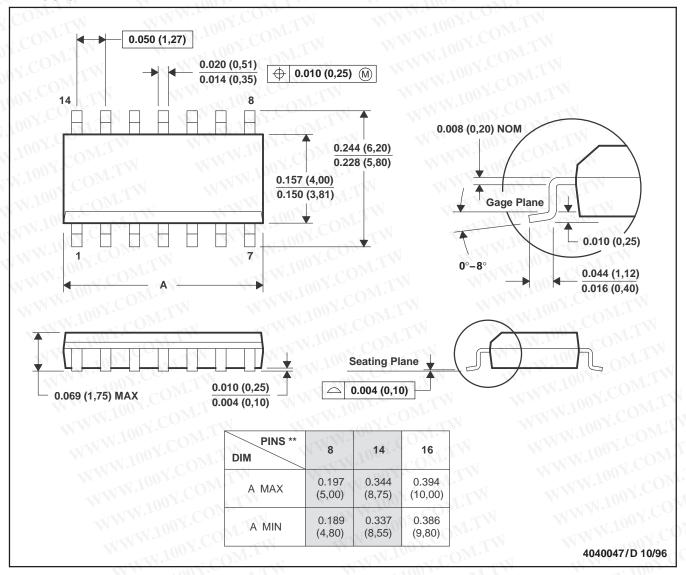
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# **MECHANICAL DATA**

# D (R-PDSO-G\*\*)

#### 14 PINS SHOWN

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012



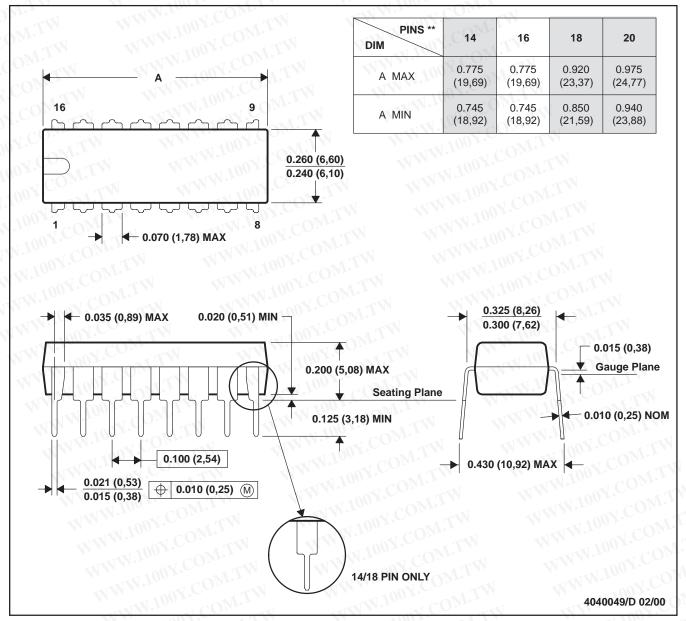
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# **MECHANICAL DATA**

# N (R-PDIP-T\*\*)

# 16 PINS SHOWN

# PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Falls within JEDEC MS-001 (20-pin package is shorter than MS-001).





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# PACKAGE OPTION ADDENDUM

22-Mar-2006

#### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN65LBC173AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LBC173ADG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LBC173ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LBC173ADRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LBC173AN	ACTIVE	PDIP	ON.	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN65LBC173ANE4	ACTIVE	PDIP	CON	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75LBC173AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75LBC173ADG4	ACTIVE	SOIC	DO	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75LBC173ADR	ACTIVE	SOIC	D CC	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75LBC173ADRG4	ACTIVE	SOIC	J.10DY.C	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75LBC173AN	ACTIVE	PDIP	NOY.	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75LBC173ANE4	ACTIVE	PDIP	M.Non	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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22-Mar-2006

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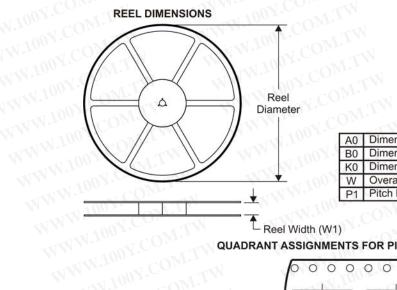
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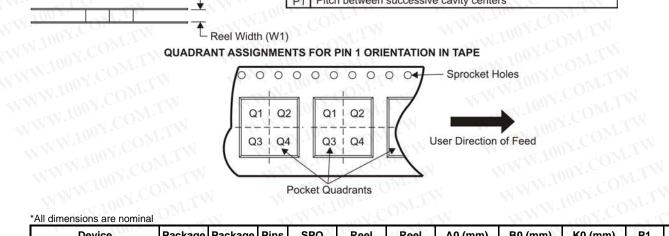


#### TAPE AND REEL INFORMATION



#### TAPE DIMENSIONS 0 $\Phi \Phi \Phi \Phi$ 0 Φ 0 0 B<sub>0</sub> → A0 ← Cavity -

		Dimension designed to accommodate the component width
Ŋ	B0	Dimension designed to accommodate the component length
7		Dimension designed to accommodate the component thickness
¥	W	Overall width of the carrier tape
	P1	Pitch between successive cavity centers



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Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadran
SN65LBC173ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN75LBC173ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

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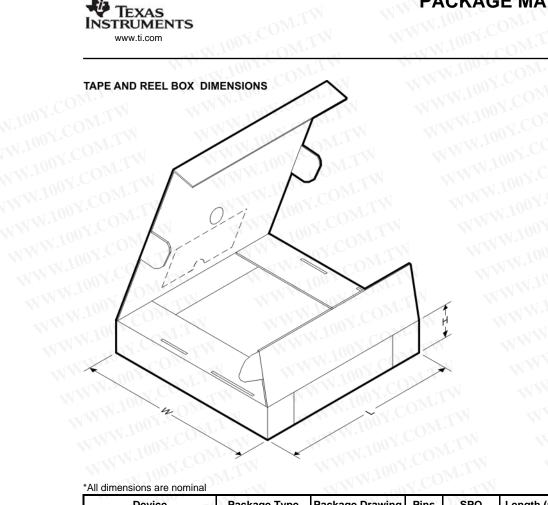
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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65LBC173ADR	SOIC	D	16	2500	333.2	345.9	28.6
SN75LBC173ADR	SOIC	D	16	2500	333.2	345.9	28.6

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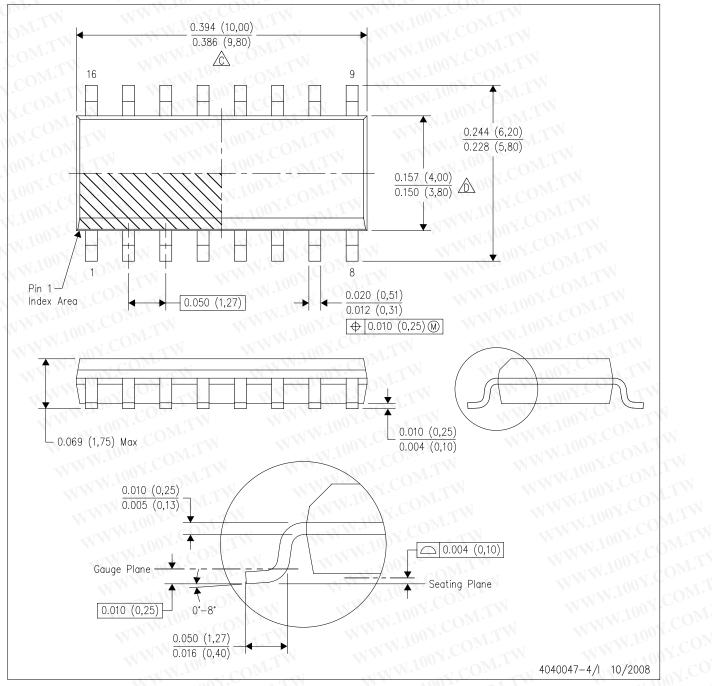
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# D (R-PDS0-G16)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- All linear dimensions are in inches (millimeters).
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

  Body width does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end. WWW.100Y.COM
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.

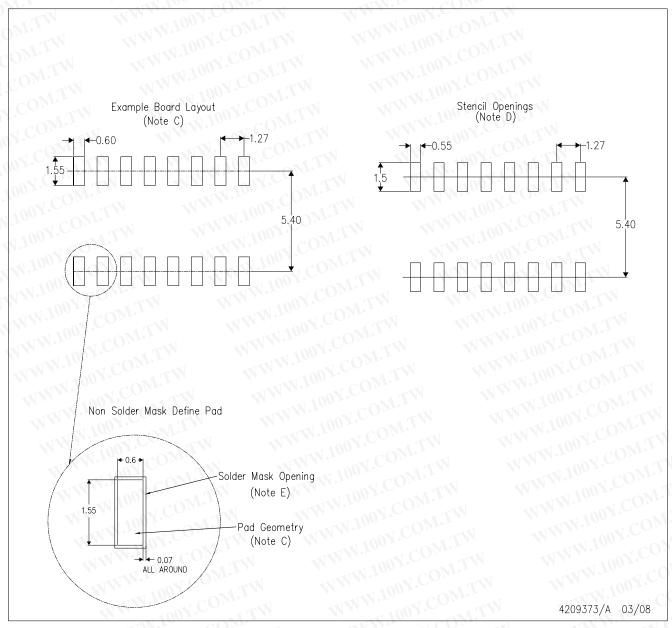


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# **LAND PATTERN**

# D(R-PDSO-G16)



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525

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E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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